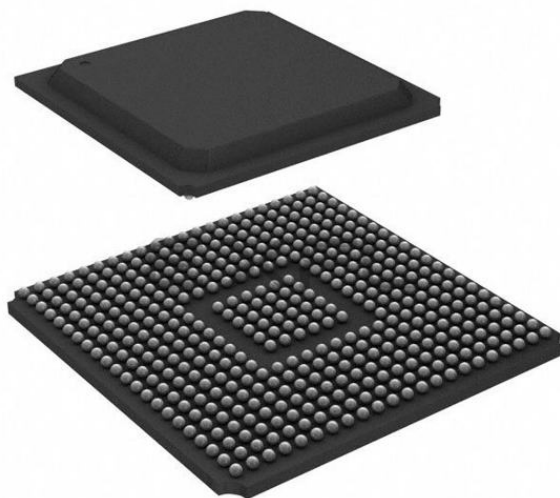




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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	352
Number of Logic Elements/Cells	3168
Total RAM Bits	221184
Number of I/O	156
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	456-BBGA
Supplier Device Package	456-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp2-6fg456c

- HyperTransport (LDT) I/O with current driver buffers
 - Built-in DDR input and output registers
- Proprietary high-performance SelectLink technology for communications between Xilinx devices
 - High-bandwidth data path
 - Double Data Rate (DDR) link
 - Web-based HDL generation methodology
- SRAM-Based In-System Configuration
 - Fast SelectMAP™ configuration
 - Triple Data Encryption Standard (DES) security option (bitstream encryption)
 - IEEE 1532 support
 - Partial reconfiguration
 - Unlimited reprogrammability
- Readback capability
- Supported by Xilinx Foundation™ and Alliance Series™ Development Systems
 - Integrated VHDL and Verilog design flows
 - ChipScope™ Integrated Logic Analyzer
- 0.13 μm Nine-Layer Copper Process with 90 nm High-Speed Transistors
- 1.5V (V_{CCINT}) core power supply, dedicated 2.5V V_{CCAUX} auxiliary and V_{CCO} I/O power supplies
- IEEE 1149.1 Compatible Boundary-Scan Logic Support
- Flip-Chip and Wire-Bond Ball Grid Array (BGA) Packages in Standard 1.00 mm Pitch.
- Wire-Bond BGA Devices Available in Pb-Free Packaging (www.xilinx.com/pbfree)
- Each Device 100% Factory Tested

General Description

The Virtex-II Pro and Virtex-II Pro X families contain platform FPGAs for designs that are based on IP cores and customized modules. The family incorporates multi-gigabit transceivers and PowerPC CPU blocks in Virtex-II Pro Series FPGA architecture. It empowers complete solutions for telecommunication, wireless, networking, video, and DSP applications.

The leading-edge 0.13 μm CMOS nine-layer copper process and Virtex-II Pro architecture are optimized for high performance designs in a wide range of densities. Combining a wide variety of flexible features and IP cores, the Virtex-II Pro family enhances programmable logic design capabilities and is a powerful alternative to mask-programmed gate arrays.

Architecture

Array Overview

Virtex-II Pro and Virtex-II Pro X devices are user-programmable gate arrays with various configurable elements and embedded blocks optimized for high-density and high-performance system designs. Virtex-II Pro devices implement the following functionality:

- Embedded high-speed serial transceivers enable data bit rate up to 3.125 Gb/s per channel (RocketIO) or 6.25 Gb/s (RocketIO X).
- Embedded IBM PowerPC 405 RISC processor blocks provide performance up to 400 MHz.
- SelectIO-Ultra blocks provide the interface between package pins and the internal configurable logic. Most popular and leading-edge I/O standards are supported by the programmable IOBs.
- Configurable Logic Blocks (CLBs) provide functional elements for combinatorial and synchronous logic, including basic storage elements. BUFTs (3-state buffers) associated with each CLB element drive dedicated segmentable horizontal routing resources.

- Block SelectRAM+ memory modules provide large 18 Kb storage elements of True Dual-Port RAM.
- Embedded multiplier blocks are 18-bit x 18-bit dedicated multipliers.
- Digital Clock Manager (DCM) blocks provide self-calibrating, fully digital solutions for clock distribution delay compensation, clock multiplication and division, and coarse- and fine-grained clock phase shifting.

A new generation of programmable routing resources called Active Interconnect Technology interconnects all these elements. The general routing matrix (GRM) is an array of routing switches. Each programmable element is tied to a switch matrix, allowing multiple connections to the general routing matrix. The overall programmable interconnection is hierarchical and supports high-speed designs.

All programmable elements, including the routing resources, are controlled by values stored in static memory cells. These values are loaded in the memory cells during configuration and can be reloaded to change the functions of the programmable elements.

Features

This section briefly describes Virtex-II Pro / Virtex-II Pro X features. For more details, refer to [Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Functional Description](#).

RocketIO / RocketIO X MGT Cores

The RocketIO and RocketIO X Multi-Gigabit Transceivers are flexible parallel-to-serial and serial-to-parallel embedded transceiver cores used for high-bandwidth interconnection between buses, backplanes, or other subsystems.

Multiple user instantiations in an FPGA are possible, providing up to 100 Gb/s (RocketIO) or 170 Gb/s (RocketIO X) of full-duplex raw data transfer. Each channel can be operated at a maximum data transfer rate of 3.125 Gb/s (RocketIO) or 6.25 Gb/s (RocketIO X).

RXP and RXN as shown in Figure 5. This supports multiple termination styles, including high-side, low-side, and differential (floating or active). This configuration supports receiver termination compatible to Virtex-II Pro devices,

using a CML (high-side) termination to an active supply of 1.8V – 2.5V. For DC coupling of two Virtex-II Pro X devices, a 1.5V CML termination for VTRX is recommended.

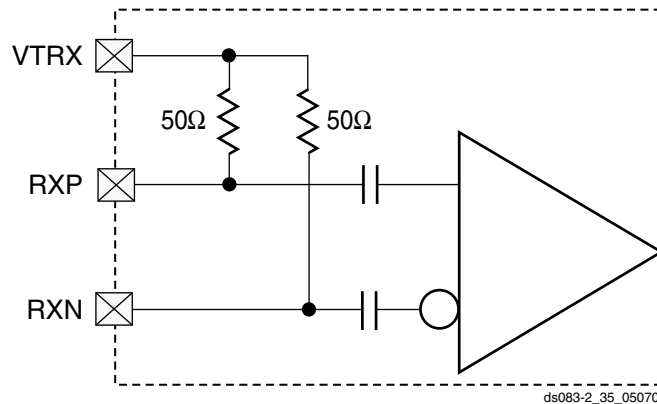


Figure 5: RocketIO X Receive Termination

PCS

Fabric Data Interface

Internally, the PCS operates in either 2-byte mode (16/20 bits) or 4-byte mode (32/40 bits). When in 2-byte mode, the FPGA fabric interface can either be 1, 2, or 4 bytes wide. When in 4-byte mode, the FPGA fabric interface can either be 4 or 8 bytes wide. When accompanied by the predefined modes of the PMA, the user thus has a large combination of protocols and data rates from which to choose.

USRCLK2 clocks data on the fabric side, while USRCLK clocks data on the PCS side. This creates distinct USRCLK/USRCLK2 frequency ratios for different combinations of fabric and internal data widths. Table 2 summarizes the USRCLK2-to-USRCLK ratios for the different possible combinations of data widths.

Table 2: Clock Ratios for Various Data Widths

Fabric Data Width	Frequency Ratio of USRCLK:USRCLK2	
	2-Byte Internal Data Width	4-Byte Internal Data Width
1 byte	1:2 ⁽¹⁾	N/A
2 byte	1:1	N/A
4 byte	2:1 ⁽¹⁾	1:1
8 byte	N/A	2:1 ⁽¹⁾

Notes:

- Each edge of slower clock must align with falling edge of faster clock.

As a general guide, use 2-byte internal data width mode when the serial speed is below 5 Gb/s, and 4-byte internal data width mode when the serial speed is greater than 5 Gb/s. In 2-byte mode, the PCS processes 4-byte data every other byte.

No fixed phase relationship is assumed between REFCLK, RXRECCLK, and/or any other clock that is not tied to either of these clocks. When RXUSRCLK and RXUSRCLK2 have different frequencies, each edge of the slower clock is aligned to a falling edge of the faster clock. The same relationships apply to TXUSRCLK and TXUSRCLK2.

FPGA Transmit Interface

The FPGA can send either one, two, or four characters of data to the transmitter. Each character can be either 8 bits or 10 bits wide. If 8-bit data is applied, the additional inputs become control signals for the 8B/10B encoder. When the 8B/10B encoder is bypassed, the 10-bit character order is generated as follows:

TXCHARDISPMODE[0] (first bit transmitted)
TXCHARDISPVAL[0]
TXDATA[7:0] (last bit transmitted is TXDATA[0])

64B/66B Encoder/Decoder

The RocketIO X PCS features a 64B/66B encoder/decoder, scrambler/descrambler, and gearbox functions that can be bypassed as needed. The encoder is compliant with IEEE 802.3ae specifications.

Scrambler/Gearbox

The bypassable scrambler operates on the read side of the transmit FIFO. The scrambler uses the following generator polynomial to scramble 64B/66B payload data:

$$G(x) = 1 + x^{39} + x^{58}$$

The scrambler works in conjunction with the gearbox, which frames 64B/66B data for the PMA. The gearbox should always be enabled when using the 64B/66B protocol.

memory protection. Working with appropriate system-level software, the MMU provides the following functions:

- Translation of the 4 GB effective address space into physical addresses
- Independent enabling of instruction and data translation/protection
- Page-level access control using the translation mechanism
- Software control of page replacement strategy
- Additional control over protection using zones
- Storage attributes for cache policy and speculative memory access control

The MMU can be disabled under software control. If the MMU is not used, the PPC405 core provides other storage control mechanisms.

Translation Look-Aside Buffer (TLB)

The Translation Look-Aside Buffer (TLB) is the hardware resource that controls translation and protection. It consists of 64 entries, each specifying a page to be translated. The TLB is fully associative; a given page entry can be placed anywhere in the TLB. The translation function of the MMU occurs pre-cache. Cache tags and indexing use physical addresses.

Software manages the establishment and replacement of TLB entries. This gives system software significant flexibility in implementing a custom page replacement strategy. For example, to reduce TLB thrashing or translation delays, software can reserve several TLB entries in the TLB for globally accessible static mappings. The instruction set provides several instructions used to manage TLB entries. These instructions are privileged and require the software to be executing in supervisor state. Additional TLB instructions are provided to move TLB entry fields to and from GPRs.

The MMU divides logical storage into pages. Eight page sizes (1 KB, 4 KB, 16 KB, 64 KB, 256 KB, 1 MB, 4 MB, and 16 MB) are simultaneously supported, such that, at any given time, the TLB can contain entries for any combination of page sizes. In order for a logical to physical translation to exist, a valid entry for the page containing the logical address must be in the TLB. Addresses for which no TLB entry exists cause TLB-Miss exceptions.

To improve performance, four instruction-side and eight data-side TLB entries are kept in shadow arrays. The shadow arrays allow single-cycle address translation and also help to avoid TLB contention between load/store and instruction fetch operations. Hardware manages the replacement and invalidation of shadow-TLB entries; no system software action is required.

Memory Protection

When address translation is enabled, the translation mechanism provides a basic level of protection.

The Zone Protection Register (ZPR) enables the system software to override the TLB access controls. For example, the ZPR provides a way to deny read access to application programs. The ZPR can be used to classify storage by type; access by type can be changed without manipulating individual TLB entries.

The PowerPC Architecture provides WIU0GE (write-back / write-through, cacheability, user-defined 0, guarded, endian) storage attributes that control memory accesses, using bits in the TLB or, when address translation is disabled, storage attribute control registers.

When address translation is enabled, storage attribute control bits in the TLB control the storage attributes associated with the current page. When address translation is disabled, bits in each storage attribute control register control the storage attributes associated with storage regions. Each storage attribute control register contains 32 fields. Each field sets the associated storage attribute for a 128 MB memory region.

Timers

The embedded PPC405 core contains a 64-bit time base and three timers, as shown in [Figure 17](#):

- Programmable Interval Timer (PIT)
- Fixed Interval Timer (FIT)
- Watchdog Timer (WDT)

The time base counter increments either by an internal signal equal to the CPU clock rate or by a separate external timer clock signal. No interrupts are generated when the time base rolls over. The three timers are synchronous with the time base.

The PIT is a 32-bit register that decrements at the same rate as the time base is incremented. The user loads the PIT register with a value to create the desired delay. When the register reaches zero, the timer stops decrementing and generates a PIT interrupt. Optionally, the PIT can be programmed to auto-reload the last value written to the PIT register, after which the PIT continues to decrement.

The FIT generates periodic interrupts based on one of four selectable bits in the time base. When the selected bit changes from 0 to 1, the PPC405 core generates a FIT interrupt.

The WDT provides a periodic critical-class interrupt based on a selected bit in the time base. This interrupt can be used for system error recovery in the event of software or system lockups. Users may select one of four time periods for the interval and the type of reset generated if the WDT expires twice without an intervening clear from software. If enabled, the watchdog timer generates a reset unless an exception handler updates the WDT status bit before the timer has completed two of the selected timer intervals.

Digitally Controlled Impedance (DCI)

Today's chip output signals with fast edge rates require termination to prevent reflections and maintain signal integrity. High pin count packages (especially ball grid arrays) can not accommodate external termination resistors.

Virtex-II Pro XCITE DCI provides controlled impedance drivers and on-chip termination for single-ended and differential I/Os. This eliminates the need for external resistors and improves signal integrity. The DCI feature can be used on any IOB by selecting one of the DCI I/O standards.

When applied to inputs, DCI provides input parallel termination. When applied to outputs, DCI provides controlled impedance drivers (series termination) or output parallel termination.

DCI operates independently on each I/O bank. When a DCI I/O standard is used in a particular I/O bank, external reference resistors must be connected to two dual-function pins on the bank. These resistors, voltage reference of N transistor (VRN) and the voltage reference of P transistor (VRP) are shown in **Figure 26**.

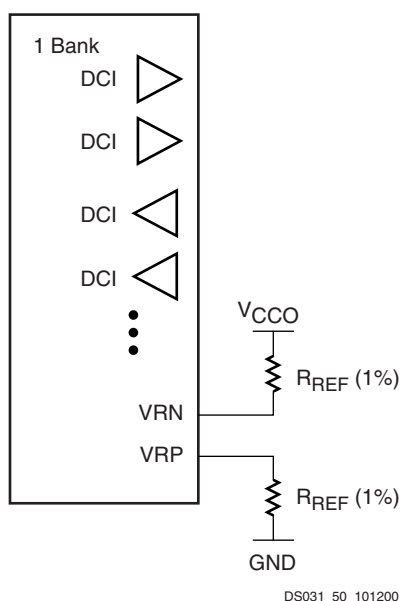


Figure 26: DCI in a Virtex-II Pro Bank

When used with a terminated I/O standard, the value of the resistors are specified by the standard (typically 50Ω). When used with a controlled impedance driver, the resistors set the output impedance of the driver within the specified range (20Ω to 100Ω). For all series and parallel terminations listed in **Table 13** and **Table 14**, the reference resistors must have the same value for any given bank. One percent resistors are recommended.

The DCI system adjusts the I/O impedance to match the two external reference resistors, or half of the reference resistors, and compensates for impedance changes due to voltage and/or temperature fluctuations. The adjustment is done by turning parallel transistors in the IOB on or off.

Controlled Impedance Drivers (Series Termination)

DCI can be used to provide a buffer with a controlled output impedance. It is desirable for this output impedance to match the transmission line impedance (Z_0). Virtex-II Pro input buffers also support LVDCI and LVDCI_DV2.

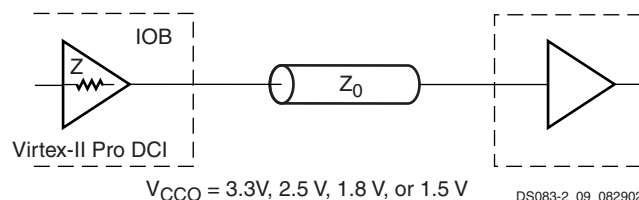


Figure 27: Internal Series Termination

Table 13: SelectIO-Ultra Controlled Impedance Buffers

V _{CCO}	DCI	DCI Half Impedance
3.3V	LVDCI_33	N/A
2.5V	LVDCI_25	LVDCI_DV2_25
1.8V	LVDCI_18	LVDCI_DV2_18
1.5V	LVDCI_15	LVDCI_DV2_15

Controlled Impedance Terminations (Parallel)

DCI also provides on-chip termination for SSTL2, SSTL18, HSTL (Class I, II, III, or IV), LVDS_25, LVDS_25, and GTL/GTLP receivers or transmitters on bidirectional lines. **Table 14** and **Table 15** list the on-chip parallel terminations available in Virtex-II Pro devices. V_{CCO} must be set according to **Table 10**. There is a V_{CCO} requirement for GTL_DCI and GTLP_DCI, due to the on-chip termination resistor.

Table 14: SelectIO-Ultra Buffers With On-Chip Parallel Termination

I/O Standard Description	IOSTANDARD Attribute	
	External Termination	On-Chip Termination
SSTL Class I, 2.5V	SSTL2_I	SSTL2_I_DCI ⁽¹⁾
SSTL Class II, 2.5V	SSTL2_II	SSTL2_II_DCI ⁽¹⁾
SSTL Class I, 1.8V	SSTL18_I	SSTL18_I_DCI
SSTL Class II, 1.8V	SSTL18_II	SSTL18_II_DCI
HSTL Class I	HSTL_I	HSTL_I_DCI
HSTL Class I, 1.8V	HSTL_I_18	HSTL_I_DCI_18
HSTL Class II	HSTL_II	HSTL_II_DCI
HSTL Class II, 1.8V	HSTL_II_18	HSTL_II_DCI_18
HSTL Class III	HSTL_III	HSTL_III_DCI
HSTL Class III, 1.8V	HSTL_III_18	HSTL_III_DCI_18
HSTL Class IV	HSTL_IV	HSTL_IV_DCI
HSTL Class IV, 1.8V	HSTL_IV_18	HSTL_IV_DCI_18
GTL	GTL	GTL_DCI
GTL Plus	GTLP	GTLP_DCI

Notes:

1. SSTL compatible.

IOB Input Switching Characteristics

Input delays associated with the pad are specified for LVC MOS 2.5V levels. For other standards, adjust the delays with the values shown in [IOB Input Switching Characteristics Standard Adjustments](#).

Table 35: IOB Input Switching Characteristics

			Speed Grade			
Description	Symbol	Device	-7	-6	-5	Units
Propagation Delays						
Pad to I output, no delay	T _{IOPI}	All	0.84	0.87	0.91	ns, max
Pad to I output, with delay	T _{IOPID}	XC2VP2	1.84	1.94	2.06	ns, max
		XC2VP4	1.84	1.94	2.06	ns, max
		XC2VP7	1.84	1.94	2.06	ns, max
		XC2VP20	2.14	2.23	2.37	ns, max
		XC2VPX20	2.14	2.23	2.37	ns, max
		XC2VP30	2.14	2.26	2.46	ns, max
		XC2VP40	2.54	2.67	2.81	ns, max
		XC2VP50	2.54	2.68	2.87	ns, max
		XC2VP70	2.54	2.72	2.91	ns, max
		XC2VPX70	2.54	2.72	2.91	ns, max
		XC2VP100	N/A	4.71	4.80	ns, max
Propagation Delays						
Pad to output IQ via transparent latch, no delay	T _{IOPLI}	All	0.86	0.89	0.93	ns, max
Pad to output IQ via transparent latch, with delay	T _{IOPLID}	XC2VP2	2.30	2.62	2.97	ns, max
		XC2VP4	2.57	2.89	3.23	ns, max
		XC2VP7	2.50	2.84	3.17	ns, max
		XC2VP20	2.65	3.04	3.42	ns, max
		XC2VPX20	2.65	3.04	3.42	ns, max
		XC2VP30	2.69	3.12	3.51	ns, max
		XC2VP40	3.30	3.63	4.03	ns, max
		XC2VP50	3.86	4.10	4.45	ns, max
		XC2VP70	4.00	4.25	4.57	ns, max
		XC2VPX70	4.00	4.25	4.57	ns, max
		XC2VP100	N/A	6.50	7.06	ns, max
Clock CLK to output IQ	T _{IOCKIQ}	All	0.60	0.60	0.67	ns, max

Table 38: IOB Output Switching Characteristics Standard Adjustments (Continued)

Description	IOSTANDARD Attribute	Timing Parameter	Speed Grade			Units
			-7	-6	-5	
HSTL, Class II	HSTL_II	T _{OHSTL_II}	0.30	0.35	0.38	ns
HSTL, Class III	HSTL_III	T _{OHSTL_III}	0.31	0.35	0.39	ns
HSTL, Class IV	HSTL_IV	T _{OHSTL_IV}	0.15	0.17	0.19	ns
HSTL, Class I, 1.8V	HSTL_I_18	T _{OHSTL_I_18}	0.56	0.64	0.70	ns
HSTL, Class II, 1.8V	HSTL_II_18	T _{OHSTL_II_18}	0.30	0.35	0.38	ns
HSTL, Class III, 1.8V	HSTL_III_18	T _{OHSTL_III_18}	0.36	0.41	0.45	ns
HSTL, Class IV, 1.8V	HSTL_IV_18	T _{OHSTL_IV_18}	0.19	0.22	0.24	ns
SSTL (Stub Series Terminated Logic), Class I, 1.8V	SSTL18_I	T _{OSSTL18_I}	0.80	0.92	1.01	ns
SSTL, Class II, 1.8V	SSTL18_II	T _{OSSTL18_II}	0.45	0.51	0.56	ns
SSTL, Class I, 2.5V	SSTL2_I	T _{OSSTL2_I}	0.63	0.72	0.79	ns
SSTL, Class II, 2.5V	SSTL2_II	T _{OSSTL2_II}	0.22	0.25	0.27	ns
LVDCI (Low-Voltage Digitally Controlled Impedance), 3.3V	LVDCI_33	T _{OLVDCI_33}	0.72	0.83	0.91	ns
LVDCI, 2.5V	LVDCI_25	T _{OLVDCI_25}	0.56	0.64	0.71	ns
LVDCI, 1.8V	LVDCI_18	T _{OLVDCI_18}	0.65	0.75	0.82	ns
LVDCI, 1.5V	LVDCI_15	T _{OLVDCI_15}	1.00	1.15	1.26	ns
LVDCI, 2.5V, Half-Impedance	LVDCI_DV2_25	T _{OLVDCI_DV2_25}	0.06	0.07	0.08	ns
LVDCI, 1.8V, Half-Impedance	LVDCI_DV2_18	T _{OLVDCI_DV2_18}	0.30	0.34	0.38	ns
LVDCI, 1.5V, Half-Impedance	LVDCI_DV2_15	T _{OLVDCI_DV2_15}	0.60	0.69	0.76	ns
HSLVDCI (High-Speed Low-Voltage DCI), 1.5V	HSLVDCI_15	T _{OHSLVDCI_15}	1.00	1.15	1.26	ns
HSLVDCI, 1.8V	HSLVDCI_18	T _{OHSLVDCI_18}	0.65	0.75	0.82	ns
HSLVDCI, 2.5V	HSLVDCI_25	T _{OHSLVDCI_25}	0.56	0.64	0.71	ns
HSLVDCI, 3.3V	HSLVDCI_33	T _{OHSLVDCI_33}	0.72	0.83	0.91	ns
GTL (Gunning Transceiver Logic) with DCI	GTL_DCI	T _{OGTL_DCI}	1.21	1.39	1.53	ns
GTL Plus with DCI	GTL_P_DCI	T _{OGTL_P_DCI}	0.05	0.06	0.07	ns
HSTL (High-Speed Transceiver Logic), Class I, with DCI	HSTL_I_DCI	T _{OHSTL_I_DCI}	0.55	0.63	0.69	ns
HSTL, Class II, with DCI	HSTL_II_DCI	T _{OHSTL_II_DCI}	0.47	0.54	0.60	ns
HSTL, Class III, with DCI	HSTL_III_DCI	T _{OHSTL_III_DCI}	0.31	0.36	0.40	ns
HSTL, Class IV, with DCI	HSTL_IV_DCI	T _{OHSTL_IV_DCI}	1.81	2.08	2.29	ns
HSTL, Class I, 1.8V, with DCI	HSTL_I_DCI_18	T _{OHSTL_I_DCI_18}	0.55	0.63	0.70	ns
HSTL, Class II, 1.8V, with DCI	HSTL_II_DCI_18	T _{OHSTL_II_DCI_18}	0.24	0.28	0.31	ns
HSTL, Class III, 1.8V, with DCI	HSTL_III_DCI_18	T _{OHSTL_III_DCI_18}	0.35	0.40	0.44	ns
HSTL, Class IV, 1.8V, with DCI	HSTL_IV_DCI_18	T _{OHSTL_IV_DCI_18}	1.48	1.70	1.87	ns
SSTL (Stub Series Terminated Logic), Class I, 1.8V, with DCI	SSTL18_I_DCI	T _{OSSTL18_I_DCI}	0.54	0.62	0.68	ns
SSTL, Class II, 1.8V, with DCI	SSTL18_II_DCI	T _{OSSTL18_II_DCI}	0.24	0.28	0.31	ns
SSTL, Class I, 2.5V, with DCI	SSTL2_I_DCI	T _{OSSTL2_I_DCI}	0.48	0.56	0.61	ns
SSTL, Class II, 2.5V, with DCI	SSTL2_II_DCI	T _{OSSTL2_II_DCI}	0.48	0.56	0.61	ns

Table 40: Output Delay Measurement Methodology

Description	IOSTANDARD Attribute	R _{REF} (Ω)	C _{REF} ⁽¹⁾ (pF)	V _{MEAS} (V)	V _{REF} (V)
SSTL (Stub Series Terminated Logic), Class I, 1.8V	SSTL18_I	50	0	V _{REF}	0.9
SSTL, Class II, 1.8V	SSTL18_II	25	0	V _{REF}	0.9
SSTL, Class I, 2.5V	SSTL2_I	50	0	V _{REF}	1.25
SSTL, Class II, 2.5V	SSTL2_II	25	0	V _{REF}	1.25
LVDS (Low-Voltage Differential Signaling), 2.5V	LVDS_25	50	0	V _{REF}	1.2
LVDS (Low-Voltage Differential Signaling), 2.5V	LVDS_25	50	0	V _{REF}	1.2
BLVDS (Bus LVDS), 2.5V	BLVDS_25	1M	0	1.2	0
LDT (HyperTransport), 2.5V	LDT_25	50	0	V _{REF}	0.6
LVPECL (Low-Voltage Positive Emitter-Coupled Logic), 2.5V	LVPECL_25	1M	0	1.23	0
LVDCI/HSLVDCI (Low-Voltage Digitally Controlled Impedance), 3.3V	LVDCI_33	1M	0	1.65	0
LVDCI/HSLVDCI, 2.5V	LVDCI_25	1M	0	1.25	0
LVDCI/HSLVDCI, 1.8V	LVDCI_18	1M	0	0.9	0
LVDCI/HSLVDCI, 1.5V	LVDCI_15	1M	0	0.75	0
HSTL (High-Speed Transceiver Logic), Class I & II, with DCI	HSTL_I_DCI, HSTL_II_DCI	50	0	V _{REF}	0.75
HSTL, Class III & IV, with DCI	HSTL_III_DCI, HSTL_IV_DCI	50	0	0.9	1.5
HSTL, Class I & II, 1.8V, with DCI	HSTL_I_DCI_18, HSTL_II_DCI_18	50	0	V _{REF}	0.9
HSTL, Class III & IV, 1.8V, with DCI	HSTL_III_DCI_18, HSTL_IV_DCI_18	50	0	1.1	1.8
SSTL (Stub Series Termini.Logic), Class I & II, 1.8V, with DCI	SSTL18_I_DCI, SSTL18_II_DCI	50	0	V _{REF}	0.9
SSTL, Class I & II, 2.5V, with DCI	SSTL2_I_DCI, SSTL2_II_DCI	50	0	V _{REF}	1.25
GTL (Gunning Transceiver Logic) with DCI	GTL_DCI	50	0	0.8	1.2
GTL Plus with DCI	GTLP_DCI	50	0	1.0	1.5

Notes:

1. C_{REF} is the capacitance of the probe, nominally 0 pF.
2. Measured as per PCI specification.
3. Measured as per PCI-X specification.

Table 7: FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
N/A	GND	R15			
N/A	GND	R16			
N/A	GND	R24			
N/A	GND	T11			
N/A	GND	T12			
N/A	GND	T13			
N/A	GND	T14			
N/A	GND	T15			
N/A	GND	T16			
N/A	GND	U6			
N/A	GND	U21			
N/A	GND	W4			
N/A	GND	W23			
N/A	GND	AA10			
N/A	GND	AA17			
N/A	GND	AC4			
N/A	GND	AC8			
N/A	GND	AC19			
N/A	GND	AC23			
N/A	GND	AD3			
N/A	GND	AD24			
N/A	GND	AE2			
N/A	GND	AE25			
N/A	GND	AF1			
N/A	GND	AF26			

Notes:

1. See [Table 4](#) for an explanation of the signals available on this pin.

Table 8: FF672 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
5	IO_L74P_5/GCLK4P	AB14			
5	IO_L73N_5	AA14			
5	IO_L73P_5	Y14			
5	IO_L69N_5/VREF_5	W14			
5	IO_L69P_5	W15			
5	IO_L68N_5	AD15			
5	IO_L68P_5	AC15			
5	IO_L67N_5	AB15			
5	IO_L67P_5	AA15			
5	IO_L45N_5/VREF_5	AC16	NC	NC	
5	IO_L45P_5	AB16	NC	NC	
5	IO_L44N_5	Y15	NC	NC	
5	IO_L44P_5	Y16	NC	NC	
5	IO_L43N_5	AC17	NC	NC	
5	IO_L43P_5	AB17	NC	NC	
5	IO_L39N_5	AA16	NC	NC	
5	IO_L39P_5	AA17	NC	NC	
5	IO_L38N_5	W16	NC	NC	
5	IO_L38P_5	Y17	NC	NC	
5	IO_L37N_5	AD18	NC	NC	
5	IO_L37P_5	AC18	NC	NC	
5	IO_L09N_5/VREF_5	AA18			
5	IO_L09P_5	Y18			
5	IO_L08N_5	AF19			
5	IO_L08P_5	AE19			
5	IO_L07N_5/VREF_5	AD19			
5	IO_L07P_5	AC19			
5	IO_L06N_5/VRP_5	AB18			
5	IO_L06P_5/VRN_5	AB19			
5	IO_L05_5/No_Pair	Y19			
5	IO_L03N_5/D4	AA19			
5	IO_L03P_5/D5	AA20			
5	IO_L02N_5/D6	AC20			
5	IO_L02P_5/D7	AB20			
5	IO_L01N_5/RDWR_B	AD21			
5	IO_L01P_5/CS_B	AC21			

Table 9: FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
4	IO_L05_4/No_Pair		AD8			
4	IO_L06N_4/VRP_4		AG8			
4	IO_L06P_4/VRN_4		AH8			
4	IO_L07N_4		AC10			
4	IO_L07P_4/VREF_4		AD10			
4	IO_L08N_4		AE7			
4	IO_L08P_4		AE8			
4	IO_L09N_4		AJ8			
4	IO_L09P_4/VREF_4		AK8			
4	IO_L37N_4		AC11			
4	IO_L37P_4		AD11			
4	IO_L38N_4		AF8			
4	IO_L38P_4		AF9			
4	IO_L39N_4		AF10			
4	IO_L39P_4		AG10			
4	IO_L43N_4		AC12			
4	IO_L43P_4		AD12			
4	IO_L44N_4		AE9			
4	IO_L44P_4		AE10			
4	IO_L45N_4		AH9			
4	IO_L45P_4/VREF_4		AJ9			
4	IO_L46N_4		AC13	NC		
4	IO_L46P_4		AD13	NC		
4	IO_L47N_4		AE11	NC		
4	IO_L47P_4		AE12	NC		
4	IO_L48N_4		AH10	NC		
4	IO_L48P_4		AH11	NC		
4	IO_L49N_4		AB14	NC		
4	IO_L49P_4		AC14	NC		
4	IO_L50_4/No_Pair		AF11	NC		
4	IO_L53_4/No_Pair		AG11	NC		
4	IO_L54N_4		AJ10	NC		
4	IO_L54P_4		AK10	NC		
4	IO_L56N_4		AF12	NC		
4	IO_L56P_4		AF13	NC		
4	IO_L57N_4		AG13	NC		

Table 9: FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
4	IO_L57P_4/VREF_4		AH13	NC		
4	IO_L67N_4		AB15			
4	IO_L67P_4		AC15			
4	IO_L68N_4		AD14			
4	IO_L68P_4		AE14			
4	IO_L69N_4		AF14			
4	IO_L69P_4/VREF_4		AG14			
4	IO_L73N_4		AD15			
4	IO_L73P_4		AE15			
4	IO_L74N_4/GCLK3S		AF15			
4	IO_L74P_4/GCLK2P		AG15			
4	IO_L75N_4/GCLK1S		AH15			
4	IO_L75P_4/GCLK0P		AJ15			
5	IO_L75N_5/GCLK7S	BREFCLKN	AJ16			
5	IO_L75P_5/GCLK6P	BREFCLKP	AH16			
5	IO_L74N_5/GCLK5S		AG16			
5	IO_L74P_5/GCLK4P		AF16			
5	IO_L73N_5		AE16			
5	IO_L73P_5		AD16			
5	IO_L69N_5/VREF_5		AG17			
5	IO_L69P_5		AF17			
5	IO_L68N_5		AE17			
5	IO_L68P_5		AD17			
5	IO_L67N_5		AC16			
5	IO_L67P_5		AB16			
5	IO_L57N_5/VREF_5		AH18	NC		
5	IO_L57P_5		AG18	NC		
5	IO_L56N_5		AF18	NC		
5	IO_L56P_5		AF19	NC		
5	IO_L54N_5		AK21	NC		
5	IO_L54P_5		AJ21	NC		
5	IO_L53_5/No_Pair		AG20	NC		
5	IO_L50_5/No_Pair		AF20	NC		
5	IO_L49N_5		AC17	NC		
5	IO_L49P_5		AB17	NC		

Table 9: FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
6	IO_L86P_6		T23			
6	IO_L86N_6		T24			
6	IO_L87P_6		U28			
6	IO_L87N_6/VREF_6		U29			
6	IO_L88P_6		T27			
6	IO_L88N_6		T28			
6	IO_L89P_6		T25			
6	IO_L89N_6		T26			
6	IO_L90P_6		V30			
6	IO_L90N_6		U30			
7	IO_L90P_7		R28			
7	IO_L90N_7		R27			
7	IO_L89P_7		R26			
7	IO_L89N_7		R25			
7	IO_L88P_7		T29			
7	IO_L88N_7/VREF_7		R29			
7	IO_L87P_7		P27			
7	IO_L87N_7		P26			
7	IO_L86P_7		R24			
7	IO_L86N_7		R23			
7	IO_L85P_7		P29			
7	IO_L85N_7		P28			
7	IO_L60P_7		N28			
7	IO_L60N_7		N27			
7	IO_L59P_7		P24			
7	IO_L59N_7		P23			
7	IO_L58P_7		P30			
7	IO_L58N_7/VREF_7		N30			
7	IO_L57P_7		M28			
7	IO_L57N_7		M27			
7	IO_L56P_7		R22			
7	IO_L56N_7		P22			
7	IO_L55P_7		N29			
7	IO_L55N_7		M29			
7	IO_L54P_7		L27			

Table 9: FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
N/A	VCCINT		Y13			
N/A	VCCINT		Y12			
N/A	VCCINT		W20			
N/A	VCCINT		W11			
N/A	VCCINT		V20			
N/A	VCCINT		V11			
N/A	VCCINT		U20			
N/A	VCCINT		U11			
N/A	VCCINT		T20			
N/A	VCCINT		T11			
N/A	VCCINT		R20			
N/A	VCCINT		R11			
N/A	VCCINT		P20			
N/A	VCCINT		P11			
N/A	VCCINT		N20			
N/A	VCCINT		N11			
N/A	VCCINT		M20			
N/A	VCCINT		M11			
N/A	VCCINT		L19			
N/A	VCCINT		L18			
N/A	VCCINT		L17			
N/A	VCCINT		L16			
N/A	VCCINT		L15			
N/A	VCCINT		L14			
N/A	VCCINT		L13			
N/A	VCCINT		L12			
N/A	GND		AK22			
N/A	GND		AK9			
N/A	GND		AJ29			
N/A	GND		AJ2			
N/A	GND		AH28			
N/A	GND		AH17			
N/A	GND		AH14			
N/A	GND		AH3			
N/A	GND		AG27			
N/A	GND		AG22			

Table 10: FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
4	VCCO_4	AD15				
4	VCCO_4	AJ10				
4	VCCO_4	AK15				
4	VCCO_4	AM6				
5	VCCO_5	AC18				
5	VCCO_5	AC19				
5	VCCO_5	AC20				
5	VCCO_5	AC21				
5	VCCO_5	AC22				
5	VCCO_5	AD20				
5	VCCO_5	AD21				
5	VCCO_5	AD22				
5	VCCO_5	AD23				
5	VCCO_5	AJ25				
5	VCCO_5	AK20				
5	VCCO_5	AM29				
6	VCCO_6	V23				
6	VCCO_6	W23				
6	VCCO_6	Y23				
6	VCCO_6	Y24				
6	VCCO_6	Y30				
6	VCCO_6	AA23				
6	VCCO_6	AA24				
6	VCCO_6	AB23				
6	VCCO_6	AB24				
6	VCCO_6	AC24				
6	VCCO_6	AE29				
6	VCCO_6	AJ32				
7	VCCO_7	F32				
7	VCCO_7	K29				
7	VCCO_7	M24				
7	VCCO_7	N23				
7	VCCO_7	N24				
7	VCCO_7	P23				
7	VCCO_7	P24				
7	VCCO_7	R23				
7	VCCO_7	R24				
7	VCCO_7	R30				

Table 11: FF1148 — XC2VP40 and XC2VP50

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
0	IO_L43N_0	B22		
0	IO_L43P_0	C22		
0	IO_L44N_0	K21		
0	IO_L44P_0	L21		
0	IO_L45N_0	G21		
0	IO_L45P_0/VREF_0	H21		
0	IO_L46N_0	E21		
0	IO_L46P_0	F21		
0	IO_L47N_0	K20		
0	IO_L47P_0	L20		
0	IO_L48N_0	C21		
0	IO_L48P_0	D21		
0	IO_L49N_0	A21		
0	IO_L49P_0	B21		
0	IO_L50_0/No_Pair	G20		
0	IO_L53_0/No_Pair	H19		
0	IO_L54N_0	E20		
0	IO_L54P_0	F20		
0	IO_L55N_0	C20		
0	IO_L55P_0	D19		
0	IO_L56N_0	K19		
0	IO_L56P_0	L19		
0	IO_L57N_0	A20		
0	IO_L57P_0/VREF_0	B20		
0	IO_L66N_0	F19	NC	
0	IO_L66P_0/VREF_0	G19	NC	
0	IO_L67N_0	B19		
0	IO_L67P_0	C19		
0	IO_L68N_0	H18		
0	IO_L68P_0	J18		
0	IO_L69N_0	F18		
0	IO_L69P_0/VREF_0	G18		
0	IO_L73N_0	D18		
0	IO_L73P_0	E18		
0	IO_L74N_0/GCLK7P	K18		
0	IO_L74P_0/GCLK6S	L18		
0	IO_L75N_0/GCLK5P	B18		
0	IO_L75P_0/GCLK4S	C18		

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
3	IO_L90P_3	AA8		
3	IO_L89N_3	Y11		
3	IO_L89P_3	Y12		
3	IO_L88N_3	AA5		
3	IO_L88P_3	AA6		
3	IO_L87N_3/VREF_3	AA3		
3	IO_L87P_3	AA4		
3	IO_L86N_3	Y13		
3	IO_L86P_3	AA13		
3	IO_L85N_3	AB7		
3	IO_L85P_3	AB8		
3	IO_L60N_3	AB5		
3	IO_L60P_3	AB6		
3	IO_L59N_3	AA9		
3	IO_L59P_3	AA10		
3	IO_L58N_3	AB3		
3	IO_L58P_3	AB4		
3	IO_L57N_3/VREF_3	AB1		
3	IO_L57P_3	AB2		
3	IO_L56N_3	AA11		
3	IO_L56P_3	AA12		
3	IO_L55N_3	AC5		
3	IO_L55P_3	AC6		
3	IO_L54N_3	AC1		
3	IO_L54P_3	AC2		
3	IO_L53N_3	AB9		
3	IO_L53P_3	AB10		
3	IO_L52N_3	AC8		
3	IO_L52P_3	AD8		
3	IO_L51N_3/VREF_3	AC4		
3	IO_L51P_3	AD4		
3	IO_L50N_3	AB11		
3	IO_L50P_3	AB12		
3	IO_L49N_3	AD6		
3	IO_L49P_3	AD7		
3	IO_L48N_3	AD2		
3	IO_L48P_3	AD3		
3	IO_L47N_3	AC9		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
4	IO_L09N_4		AR11		
4	IO_L09P_4/VREF_4		AP11		
4	IO_L19N_4		AV11		
4	IO_L19P_4		AU11		
4	IO_L20N_4		AY10		
4	IO_L20P_4		AY11		
4	IO_L21N_4		AN12		
4	IO_L21P_4		AM12		
4	IO_L25N_4		AR12		
4	IO_L25P_4		AP12		
4	IO_L26N_4		AT12		
4	IO_L26P_4		AU12		
4	IO_L27N_4		AW12		
4	IO_L27P_4/VREF_4		AV12		
4	IO_L28N_4		AM13		
4	IO_L28P_4		AL13		
4	IO_L29N_4		AP13		
4	IO_L29P_4		AN13		
4	IO_L30N_4		AT13		
4	IO_L30P_4		AR13		
4	IO_L34N_4		AV13		
4	IO_L34P_4		AU13		
4	IO_L35N_4		AW13		
4	IO_L35P_4		AY13		
4	IO_L36N_4		AL15		
4	IO_L36P_4/VREF_4		AL14		
4	IO_L78N_4		AN14	NC	
4	IO_L78P_4		AM14	NC	
4	IO_L83_4/No_Pair		AR14	NC	
4	IO_L84N_4		AU14	NC	
4	IO_L84P_4		AT14	NC	
4	IO_L85N_4		AW14	NC	
4	IO_L85P_4		AV14	NC	
4	IO_L86N_4		AM15	NC	
4	IO_L86P_4		AN15	NC	
4	IO_L87N_4		AR15	NC	

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
6	IO_L52N_6		AE42		
6	IO_L53P_6		AE32		
6	IO_L53N_6		AE33		
6	IO_L54P_6		AD35		
6	IO_L54N_6		AD36		
6	IO_L55P_6		AD37		
6	IO_L55N_6		AD38		
6	IO_L56P_6		AD31		
6	IO_L56N_6		AD32		
6	IO_L57P_6		AD39		
6	IO_L57N_6/VREF_6		AD40		
6	IO_L58P_6		AD41		
6	IO_L58N_6		AD42		
6	IO_L59P_6		AD33		
6	IO_L59N_6		AD34		
6	IO_L60P_6		AC33		
6	IO_L60N_6		AC34		
6	IO_L85P_6		AC36		
6	IO_L85N_6		AC37		
6	IO_L86P_6		AC31		
6	IO_L86N_6		AC32		
6	IO_L87P_6		AC39		
6	IO_L87N_6/VREF_6		AC40		
6	IO_L88P_6		AB33		
6	IO_L88N_6		AB34		
6	IO_L89P_6		AB36		
6	IO_L89N_6		AB37		
6	IO_L90P_6		AB39		
6	IO_L90N_6		AB40		
7	IO_L90P_7		AA39		
7	IO_L90N_7		AA40		
7	IO_L89P_7		AB31		
7	IO_L89N_7		AA31		
7	IO_L88P_7		AA36		
7	IO_L88N_7/VREF_7		AA37		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
3	VCCO_3		AD14		
3	VCCO_3		AC15		
3	VCCO_3		AC14		
3	VCCO_3		AC8		
3	VCCO_3		AC5		
3	VCCO_3		AB15		
3	VCCO_3		AB14		
4	VCCO_4		AW18		
4	VCCO_4		AT20		
4	VCCO_4		AT15		
4	VCCO_4		AT11		
4	VCCO_4		AP18		
4	VCCO_4		AP14		
4	VCCO_4		AJ21		
4	VCCO_4		AJ20		
4	VCCO_4		AJ19		
4	VCCO_4		AJ18		
4	VCCO_4		AJ17		
4	VCCO_4		AH21		
4	VCCO_4		AH20		
4	VCCO_4		AH19		
4	VCCO_4		AH18		
5	VCCO_5		AW25		
5	VCCO_5		AT32		
5	VCCO_5		AT28		
5	VCCO_5		AT23		
5	VCCO_5		AP29		
5	VCCO_5		AP25		
5	VCCO_5		AJ26		
5	VCCO_5		AJ25		
5	VCCO_5		AJ24		
5	VCCO_5		AJ23		
5	VCCO_5		AJ22		
5	VCCO_5		AH25		
5	VCCO_5		AH24		
5	VCCO_5		AH23		

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
7	IO_L87P_7	AA37	
7	IO_L87N_7	AA38	
7	IO_L86P_7	AA33	
7	IO_L86N_7	AA34	
7	IO_L85P_7	Y40	
7	IO_L85N_7	Y41	
7	IO_L60P_7	W41	
7	IO_L60N_7	W42	
7	IO_L59P_7	AA31	
7	IO_L59N_7	AA32	
7	IO_L58P_7	V40	
7	IO_L58N_7/VREF_7	W40	
7	IO_L57P_7	W37	
7	IO_L57N_7	W38	
7	IO_L56P_7	Y36	
7	IO_L56N_7	Y37	
7	IO_L55P_7	V41	
7	IO_L55N_7	V42	
7	IO_L54P_7	V38	
7	IO_L54N_7	V39	
7	IO_L53P_7	Y31	
7	IO_L53N_7	Y32	
7	IO_L52P_7	U40	
7	IO_L52N_7/VREF_7	U41	
7	IO_L51P_7	T40	
7	IO_L51N_7	U39	
7	IO_L50P_7	Y35	
7	IO_L50N_7	W36	
7	IO_L49P_7	T37	
7	IO_L49N_7	U37	
7	IO_L48P_7	T41	
7	IO_L48N_7	T42	
7	IO_L47P_7	Y33	
7	IO_L47N_7	W34	
7	IO_L46P_7	T38	
7	IO_L46N_7/VREF_7	T39	
7	IO_L45P_7	R36	